

LINEAR TECHNOLOGY MATERIALS DECLARATION

1tc1867cgn#trpbf

(Engineering Calculation)

SSOP

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TOTAL MASS (g) : 0.083274

| COMPONENT MATERIAL | VENDOR/ INDUSTRY NAMES | CONSTITUENT NAME | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL PKG. | | |
|--------------------------|----------------------------------|--------------------------------|------------|----------------------|-------------------------------|---------------------------------|----------------|----------------------|
| Active Device | Linear Technology | Silicon (Si) | 7440-21-3 | 0.004138 | 1000000 | 49691.3359375 | | |
| Die Coat | Dow Corning | Silicone | 69430-27-9 | 0.000000 | 0 | 0 | | |
| Lead Frame | Cu | Copper (Cu) | 7440-50-8 | 0.029933 | 975000 | 359451.625 | | |
| | | Iron (Fe) | 7439-89-6 | 0.000737 | 24000 | 8850.29394531 | | |
| | | Phosphorus (P) | 7723-14-0 | 0.000009 | 300 | 108.076858521 | | |
| | | Zinc (Zn) | 7440-66-6 | 0.000021 | 700 | 252.179336548 | | |
| | | Nickel (Ni) | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Silicon (Si) | 7440-21-3 | 0.000000 | 0 | 0 | | |
| | | Magnesium (Mg) | 7439-95-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| Lead Frame Total: | | | | 0.030700 | 1000000 | 368662.15625 | | |
| Plating | PMI | Exter. Plating Pb | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Exter. Plating Sn | 7440-31-5 | 0.002272 | 1000000 | 27284.3652344 | | |
| | | External Plating Total: | | | | 0.002272 | 1000000 | 27284.3652344 |
| | | Inter. Plating Ni | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Inter. Plating Ag | 7440-22-4 | 0.000246 | 1000000 | 2954.10083008 | | |
| | | Internal Plating Total: | | | | 0.000246 | 1000000 | 2954.10083008 |
| Die Attach | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag) | 7440-22-4 | 0.001132 | 750000 | 13593.6660156 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | Lead (Pb) | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.000000 | 0 | 0 | | |
| | | Indium (In) | 7440-74-6 | 0.000000 | 0 | 0 | | |
| | | Metal Oxide | | 0.000000 | 0 | 0 | | |
| | | Antimony (Sb) | 7440-36-0 | 0.000000 | 0 | 0 | | |
| | | Resin (EP) | | 0.000377 | 250000 | 4527.21923828 | | |
| Die Attach Total: | | | | 0.001509 | 1000000 | 18120.8847656 | | |
| Encapsulation | MULTI-AROMATIC RESIN Br/Sb FREE | Resin (EP) | | 0.006623 | 150000 | 79532.5546875 | | |
| | | Bromine (Br) | 40039-93-8 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.036203 | 820000 | 434745.15625 | | |
| | | Antimony Trioxide (Sb2O3) | 1309-64-4 | 0.000000 | 0 | 0 | | |
| | | Metal Hydroxide | | 0.001104 | 25000 | 13257.4277344 | | |
| | | Carbon Black (C) | 1333-86-4 | 0.000221 | 5000 | 2653.88720703 | | |
| | | Encapsulation Total: | | | | 0.044151 | 1000000 | 530189.0625 |
| Bond Wire Estimated | AFW/TANAKA/ Kn | Gold (Au) | 7440-57-5 | 0.000258 | 1000000 | 3098.203125 | | |
| | | | | | TOTAL MASS (g) : | 0.083274 | | |